



智慧財產權聲明

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eMemory, NeoBit, NeoFuse, NeoFlash, NeoEE, NeoMTP, NeoROM, EcoBit 與 NeoPUF 皆為力旺電子在台灣或其他國家之商標或服務標章。



投資安全聲明

除簡報內所提供之歷史信息外,簡報事項係屬預測性陳 述,受到風險及不確定性因素影響,可能造成實際結果 與陳述內容發生不符,這些不確定性因素包括:技術平 台是否順利導入利用、IP是否被客戶接受、客戶產品大 量量產之能力及時間、產業及市場對半導體產品之供給 及需求移轉、終端市場之穩定性及其他風險等。



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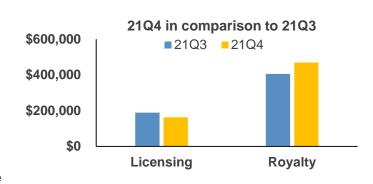
第四季及全年度綜合損益表

(thousands of NT dollars)

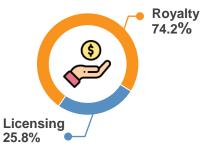
	Q4 2021 (Unaudited)	Q3 2021	Change (QoQ)	Q4 2020	Change (YoY)	FY 2021 (Unaudited)	FY 2020	Change (YoY)
Revenue	631,398	594,277	6.2%	496,682	27.1%	2,363,824	1,776,653	33.0%
Gross Margin	100%	100%	-	100%	-	100%	100%	-
Operating Expenses	299,677	277,611	7.9%	261,327	14.7%	1,095,012	954,067	14.8%
Operating Income	331,721	316,666	4.8%	235,355	40.9%	1,268,812	822,586	54.2%
Operating Margin	52.5%	53.3%	-0.8ppt	47.4%	5.1ppts	53.7%	46.3%	7.4ppts
*Net Income	287,263	277,181	3.6%	193,343	48.6%	1,101,157	707,999	55.5%
Net Margin	45.2%	46.3%	-1.1ppts	38.7%	6.5ppts	46.3%	39.8%	6.5ppts
EPS (NT\$)	3.86	3.72	3.8%	2.60	48.5%	14.78	9.52	55.3%
ROE	51.4%	53.2%	-1.8ppts	41.8%	9.6ppts	49.3%	38.3%	11.0ppts

^{*}Net income attributable to the Shareholders of the Company

第四季及全年度營收貢獻分析



Revenue Breakdown



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NT\$ Thousands	Q4 2021	Q3 2021	Change (QoQ)	Q4 2020	Change (YoY)	FY 2021	FY 2020	Change (YoY)
Licensing	162,632	188,667	-13.8%	154,472	5.3%	702,851	490,105	43.4%
Royalty	468,766	405,610	15.6%	342,210	37.0%	1,660,973	1,286,548	29.1%
Total	631,398	594,277	6.2%	496,682	27.1%	2,363,824	1,776,653	33.0%

US\$ Thousands	Q4 2021	Q3 2021	Change (QoQ)	Q4 2020	Change (YoY)	FY 2021	FY 2020	Change (YoY)
Licensing	5,855	6,778	-13.6%	5,350	9.4%	25,092	16,610	51.1%
Royalty	16,788	14,584	15.1%	11,859	41.6%	59,173	43,586	35.8%
Total	22,643	21,362	6.0%	17,209	31.6%	84,265	60,196	40.0%

第四季及全年度營收分析-產品線

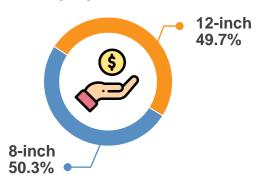
- ✓ The royalty revenue of NeoFuse up 27.3% QoQ and up 89.6% YoY due to increasing production from new and existing products from OLED, DDI, ISP, DTV, DRAM and others.
- ✓ PUF-based IP licensing in 2021 increased 140.9% YoY due to strong demand for PUF-based solution.

				Q4 2021					
	Total Revenue		Lice	Licensing Revenue			Royalty Revenue		
Technology	% of Q4 Revenue	Change (QoQ)	Change (YoY)	% of Q4 Licensing	Change (QoQ)	Change (YoY)	% of Q4 Royalty	Change (QoQ)	Change (YoY)
NeoBit	35.2%	-3.6%	0.0%	14.5%	-39.7%	-11.2%	42.4%	3.7%	1.5%
NeoFuse	57.1%	22.0%	46.6%	63.4%	10.4%	-6.3%	54.8%	27.3%	89.6%
PUF-Based	3.0%	585.6%	647.7%	11.6%	580.4%	639.6%	0.1%	2,188.9%	100.0%
MTP	4.7%	-54.5%	13.9%	10.5%	-68.2%	11.3%	2.7%	6.3%	17.6%

	FY 2021							
	Total Revenue		Licensing	Revenue	Royalty Revenue			
Technology	% of FY 2021 Revenue	Change (YoY)	% of FY 2021 Licensing	Change (YoY)	% of FY 2021 Royalty	Change (YoY)		
NeoBit	38.8%	1.5%	19.9%	45.9%	46.7%	-3.8%		
NeoFuse	51.9%	58.4%	55.4%	15.6%	50.4%	91.6%		
PUF-Based	1.2%	142.7%	4.2%	140.9%	0.0%	100.0%		
MTP	8.1%	119.2%	20.5%	220.8%	2.9%	12.1%		

第四季及全年度營收分析 – Wafer Size

Q4 Royalty Breakdown



- 8-inch wafers contributed 50.3% of royalty, up 11.2% sequentially and 13% YoY due to more production from PMIC, DDI, Fingerprint and Sensors.
- √ 12-inch wafers contributed 49.7% of royalty, up 20.3% QoQ and 74.4% YoY due to continuous production from WiFi 6/6E, OLED, ISP, DTV, DRAM and more.

Wofor Size		Q4 2021		FY 2021		
Wafer Size	% of Q4	Change (QoQ)	Change (YoY)	% of FY 2021	Change (YoY)	
8-Inch	50.3%	11.2%	13.0%	52.5%	8.9%	
12-Inch	49.7%	20.3%	74.4%	47.5%	62.4%	



eMemory Embedded Everywhere

✓ eMemory's IP seeks to penetrate across all the applications



✓ Product Applications:

eMemory's IPs are already applied into different applications, which includes PMIC, LCD Driver, Sensors, RFID, OLED Driver, Connectivity IC, DTV, STB, SSD Controller, Bluetooth, TDDI, MCU, Finger-print Sensor, Smart Meters, Surveillance, ISP, CIS, DRAM, Embedded Flash, IoT, AI and FPGA.

✓ Future Target:

AP, GPU, CPU, DPU, and Autonomous Driving



✓ Product Application with PUF-based Security IP:

PUF-based security IPs are being applied in AI, IoT, AIoT, GPS, PMIC and MCU.

✓ PUF-based Security Solutions:

Automotive, Communication, Networking and Vertical Market.



未來展望

Licensing & Royalty



✓ Licensing:

• Licensing revenue will grow due to the continued strong demand for our IPs, especially NeoFuse and PUF-related solutions.

✓ Royalty:

- 8-inch royalties will continue to grow due to the demand and content increase for PMIC, MCU, Fingerprint, and Sensor-related in 5G, Automotive, and IoT-related applications.
- 12-inch royalties will have strong growth as customers are ramping up production for TDDI, OLED, ISP, DTV, STB, WiFi 6/6E, Bluetooth, Ethernet, Switch, TWS, DRAM and others.
- Royalties for 12/16nm and 7nm FinFET have also started to contribute in the fourth quarter and is expected to be the next growth driver after 28nm.

未來展望

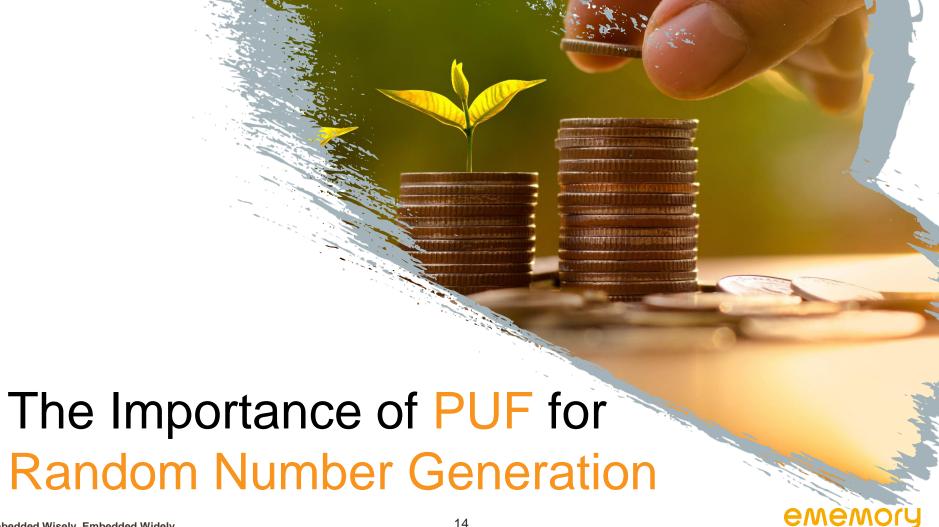
✓ New Business Development:

- The focus of our new application development is in the field of security. NeoFuse is replacing secret key storage for eFuse, and applications are migrating to more advanced processes, and was also adopted by automotive applications in 6/7nm.
- Business activities for PUF-based security solutions are continuing to progress in IoT, Industrial IoT, AI, Blockchain, FPGA, Data Processor Unit (DPU), Mobile Storage (UFS) and Automotive applications.
- PUFrt was selected by Arm for the secure sub-system of the Armv9 confidential computing architecture. This is significant breakthrough for our IP to be adopted by leading processor application markets.

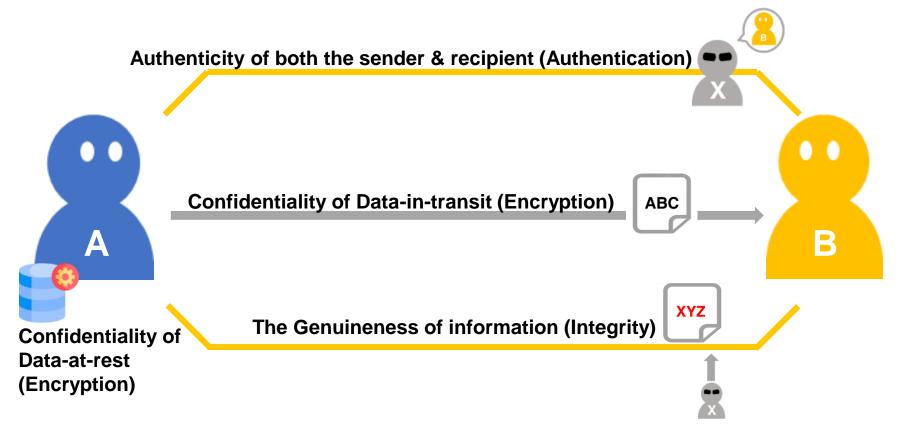
✓ New IP Technology Development:

- Integrated NeoFuse and NeoPUF IP with high security function, was verified and designed in TSMC's N5 process, supporting high-end to mid-end Mobile, Consumer, AI, Networking, 5G Infrastructure, GPU, DPU and High-performance Computing.
- ReRAM IP has been qualified on the UMC 40nm process, and tape-out has begun for the 22nm process. ReRAM will extend to advanced process nodes and specialty processes such as BCD and high voltage.
- Continue to develop new security functional IPs, including PUF-based Security Co-Processors and PUF-based Security Elements.
- Develop NeoFlash in BCD as well as 28nm and below processes to solve the technology problem of traditional embedded Flash.





Revisiting the Goals of Security

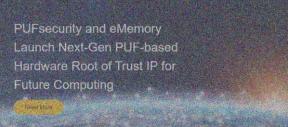


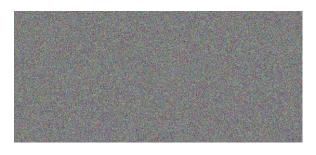
Randomness is Pivotal in Security

Introducing unpredictability significantly improves security

Ex: Encrypting a message using random numbers of different quality







Original

Poorly Random

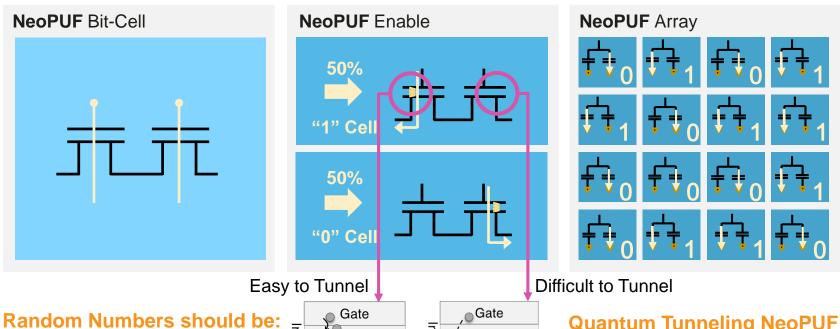
Highly Random

"The strength of a security mechanism is directly proportional to the randomness of the number it uses"

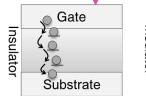
Methods of Generating Random Numbers

Software RNG	Hardware RNG
Generated from Computer Programs e.g. rand() commands	Extracted from physical sources e.g., intrinsic difference in materials
Pseudorandom	Truly Random
Requires initial seed	No seed is needed
Periodic up to a certain length	Not repeatable
Deterministic, thus reproducible Dependent SW RNG RNG Random Numbers	Non-reproducible Independent Enrollment PUF 1011001010111010 Random Numbers

On-Chip Randomness from PUF



- Electronically measurable on chip
- Unpredictable and Unrepeatable



Insulator Substrate

Quantum Tunneling NeoPUF

- Measurable tunneling current on chip
- Unique and Randomly distributed 0s & 1s

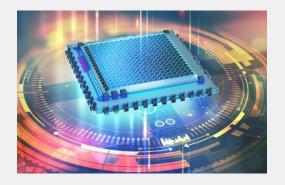
Building upon PUF-based Security

PUFrt selected by ARM for v9 CCA security



- PUFrt fully integrates Key generation, Secure Storage and tRNG
- Such Hardware Root-of-Trust is indispensable for all markets spanning cloud to mobile and automotive to IoT.

eMemory partners with Intel Foundry Service



- eMemory's OTP, PUF and Security IPs will be available in Intel's leading-edge processes
- PUF-based security enables Zero Trust and enhances supply chain security



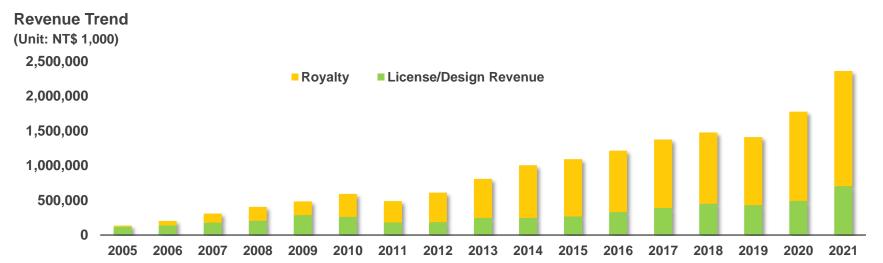
Q&A



附錄

公司介紹

✓ eMemory is the global leader of embedded non-volatile memory IP



Founded

Based in Hsinchu, Taiwan. IPO in 2011. Over 41M wafers shipped.

1000 Patents Issued

213 pending patents. 297 employees with 68% R&D personnel.

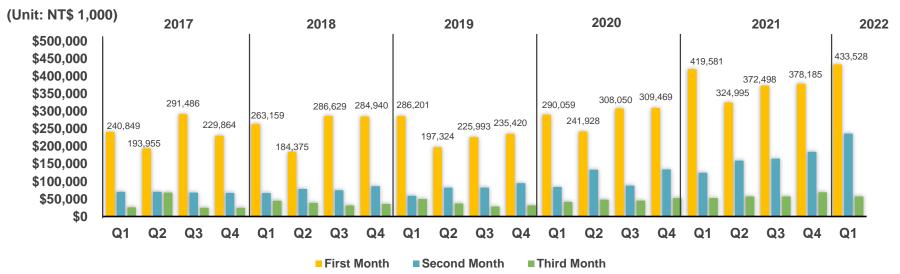
Best IP Partner

TSMC Best IP Partner Award since 2010.

ememory

每季營收

- ✓ 1st month: Receive License Fees of the month and Royalty from most foundries on previous quarter's wafer shipments.
- ✓ 2nd month: Receive License Fees of the month and Royalty from other foundries.
- √ 3rd month: License Fees Only.



全球客戶

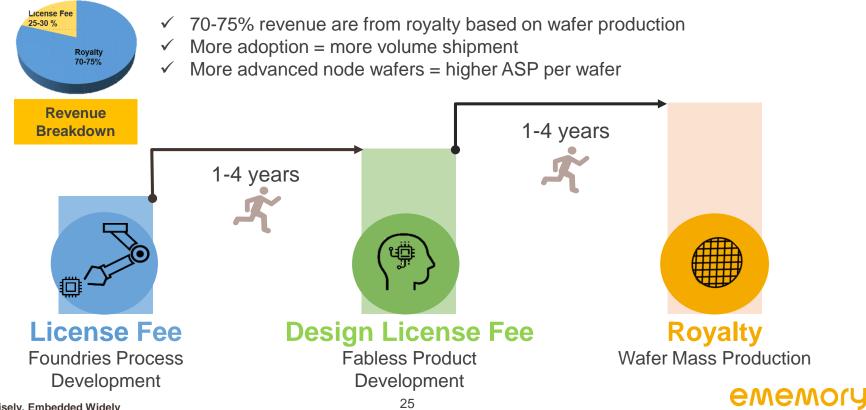
✓ Our IP solutions are adopted by leading foundries, IDMs and fabless worldwide

Country	Foundry	IDM	Fabless
Taiwan	4	1	324
China	9	0	979
Korea	4	0	94
Japan	4	7	75
North America	1	1	319
Europe	2	1	198
Others	1	0	83



營運模式

✓ Recurring royalty is the backbone of our business

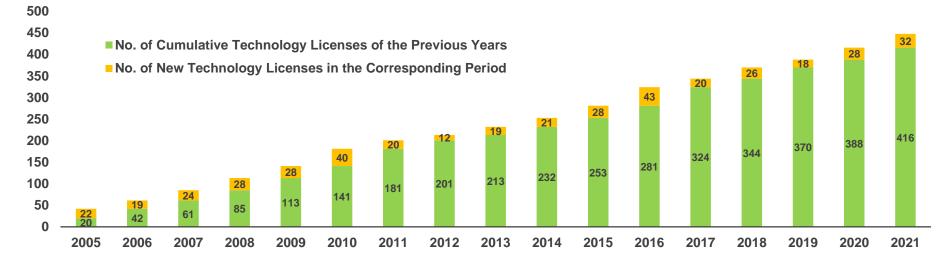


技術授權合約

Number of Licenses

Year	2016	2017	2018	2019	2020	2021
License	43	20	26	18	28	32

Note: Terms (including number of process platforms and licensing fees) for each technology license are set contractually. Payments are made according to set milestones, and there are no particular seasonal factors involved.



建構中的技術製程平台

- ✓ New technologies are being developed for 103 platforms by Q4 2021.
- ✓ 8 licensing contracts were signed.

Technology	5/6nm	7/10nm	12/16nm	22/28nm	40nm	55/65nm	80/90nm	0.11~ 0.13um	0.15~ 0.18um	>0.25um
NeoBit	-	-	-	-	-	1	1	9	11	1
NeoFuse	1	1	5	9	2	11	8	2	-	-
PUF-Based	1	-	-	-		1	-	-	-	-
MTP	1	-	-	2	-	6	3	8	20	-

Note: As of Dec 31st, 2021

建構中的技術製程平台

✓ Developments by process nodes

12" Fabs	Production	Development	IP Type	Process Type
5/6nm	2	2	OTP, PUF	FF
7/10nm	2	1	OTP, PUF	FF, FF+
12/16nm	6	5	OTP, PUF	FF, FF+, FFC. FFC+, LPP
28/22nm	40	11	OTP, PUF	LP/ULP/ULL, HPC/HPC+, HV-OLED, DRAM, SOI, ReRAM MRAM
40nm	20	2	OTP, PUF, MTP	LP/ULP, E-Flash, HV-DDI/OLED, ReRAM
55/65nm	32	19	OTP, PUF, MTP	LP/ULP, E-Flash, HV-DDI/OLED, DRAM, CIS, BCD, PM
80/90nm	22	9	OTP, MTP	HV-DDI/OLED, LP, Generic ,BCD, CIS
0.13/0.11um	20	2	OTP, MTP	HV-DDI, BCD, Generic
0.18um	1	8	OTP, MTP	BCD, Generic
Total	145	59		

8" Fabs	Production	Development	IP Type	Process Type
80/90nm	9	3	OTP	HV-DDI, LL, BCD
0.13/0.11um	74	17	OTP, MTP, PUF	HV/HV-MR, BCD, LP/LL, CIS, Green, Flash, SOI, Generic
0.18/0.16/0.152um	219	23	OTP, MTP	HV/HV-MR, BCD, LP/LL, CIS, Green, Generic
0.25um	43	1	OTP, MTP	BCD
0.3/0.35um	52	0	OTP	UHV, BCD
0.4/0.5um	11	0	ОТР	UHV, BCD
Total	408	44		

Note: As of Dec 31st, 2021

